

Listing of Claims

1-34. (Canceled).

35. (New) A device, comprising:

a first substrate having an upper surface with a gasket formed thereon, said gasket being composed of a first compliant material and at least partially coated with a hermeticity-increasing material;

a second substrate having an upper surface with at least one electrically conductive area thereon;

wherein said first substrate and said second substrate are pressed together with said upper surface of said first substrate facing said upper surface of said second substrate, such that said gasket is deformed; and

wherein said gasket and said upper surface of said second substrate form an enclosed chamber that is hermetically sealed, and wherein at least one electrically-conductive element is located within said enclosed chamber and is in direct contact with said at least one electrically conductive area on said second substrate.

36. (New) The device of claim 35, wherein said electrically-conductive element is a post composed of a second compliant material and coated with an electrically-conductive material.

37. (New) The device of claim 36, wherein at least one of said first compliant material and said second compliant material comprises a polymer.

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38. (New) The device of claim 36, wherein at least one of said first compliant material and said second compliant material comprises a polyimide.

39. (New) The device of claim 35, wherein said hermeticity-increasing material is electrically conductive.

40. (New) The device of claim 35, wherein said hermeticity-increasing material is not electrically conductive.

41. (New) The device of claim 35, wherein said gasket has an inner surface and an outer surface, and wherein an outer surface of said gasket, a portion of said upper surface of said first substrate, and a portion of said upper surface of said second substrate are coated with said hermeticity-increasing material.

42. (New) The device of claim 35, further comprising at least one non-compliant spacer formed on one of said first substrate and said second substrate.

43. (New) A device, comprising:

a first substrate having an upper surface with a gasket and at least one post formed thereon, said gasket being composed of a first compliant material and coated with a hermeticity-increasing material, and said at least one post being composed of a second compliant material and coated with an electrically-conductive material;

a second substrate having an upper surface with at least one electrically conductive area thereon;

wherein said first substrate and said second substrate are pressed together with said upper surface of said first substrate facing said upper surface of said second substrate, such that said gasket and said at least one post of said first substrate are deformed; and

wherein said gasket and said upper surface of said second substrate form an enclosed chamber that is hermetically sealed, and said at least one post is positioned within said chamber and in direct contact with said at least one electrically conductive area on said second substrate.

44. (New) The device of claim 43, wherein at least one of said first compliant material and said second compliant material comprises a polymer.

45. (New) The device of claim 43, wherein at least one of said first compliant material and said second compliant material comprises a polyimide.

46. (New) The device of claim 43, wherein said hermeticity-increasing material is electrically conductive.

47. (New) The device of claim 43, wherein said hermeticity-increasing material is not electrically conductive.

48. (New) The device of claim 43, further comprising at least one non-compliant spacer formed on one of said first substrate and said second substrate.

49. (New) A device, comprising:

a first substrate having an upper surface with a gasket and at least one post formed thereon, said gasket having an inner surface and an outer surface and being composed of a first compliant material, said at least one post being composed of a second compliant material and coated with an electrically-conductive material;

a second substrate having an upper surface with at least one electrically conductive area formed thereon;

wherein said first substrate and said second substrate are pressed together with said upper surface of said first substrate facing said upper surface of said second substrate, such that said gasket and said at least one post of said first substrate are deformed; and

wherein said outer surface of said gasket, a portion of said upper surface of said first substrate, and a portion of said upper surface of said second substrate are coated with a hermeticity-increasing material such that said inner surface of said gasket and said upper surface of said second substrate form an enclosed chamber that is hermetically sealed, and said at least one post is positioned within said enclosed chamber and in direct contact with said at least one electrically conductive area on said second substrate.

50. (New) The device of claim 49, wherein at least one of said first compliant material and said second compliant material comprises a polymer.

51. (New) The device of claim 49, wherein at least one of said first compliant material and said second compliant material comprises a polyimide.

52. (New) The device of claim 49, wherein said hermeticity-increasing material is electrically conductive.

53. (New) The device of claim 49, wherein said hermeticity-increasing material is not electrically conductive.

54. (New) The device of claim 49, further comprising at least one non-compliant spacer formed on one of said first substrate and said second substrate.